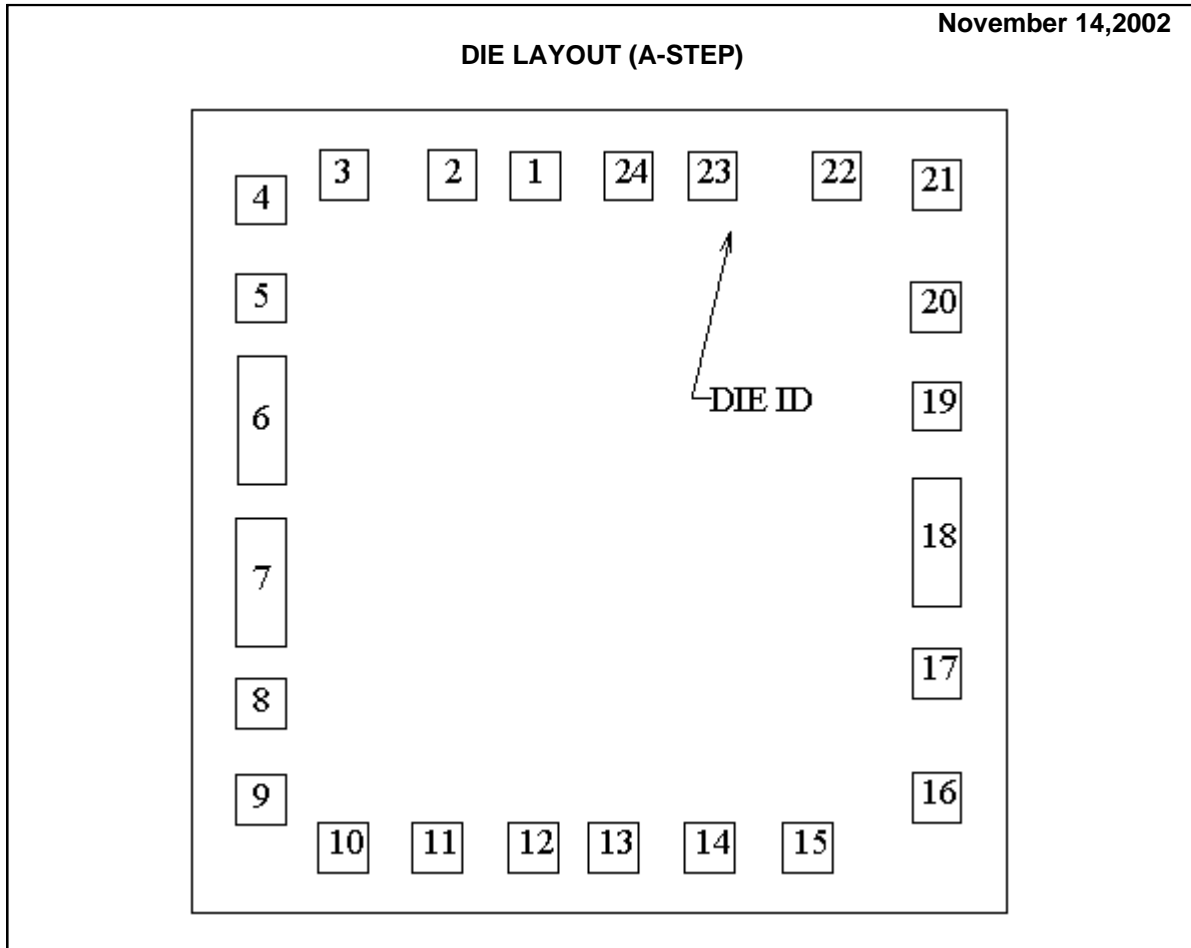


LMXXX MDA MWA EXAMPLE DIE DATASHEET
DEVICE DISCRPTION



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMXXX	Bond Pad Opening Size (min)	000μm x 000μm
Die Step	A	Bond Pad Metalization	xxx
Physical Attributes		Passivation	xxx
Wafer Diameter	000mm	Back Side Metal	xxx
Die Size (Drawn)	0μm x 0μm 0mils x 0mils	Back Side Connection	xxx
Thickness	000μm Nominal		
Min Pitch	000μm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

LMXXX MDA MWA EXAMPLE DIE DATASHEET
DEVICE DISRIPTION

Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL	PAD#	X/Y CORRINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
Signal	1	-XXX	YYY	XXX	x	YYY
Signal	2	-XXX	YYY	XXX	x	YYY
Signal	3	-XXX	YYY	XXX	x	YYY
Signal	4	-XXX	YYY	XXX	x	YYY
Signal	5	-XXX	YYY	XXX	x	YYY
Signal	6	-XXX	YYY	XXX	x	YYY
Signal	7	-XXX	-YYY	XXX	x	YYY
Signal	8	-XXX	-YYY	XXX	x	YYY
Signal	9	-XXX	-YYY	XXX	x	YYY
Signal	10	-XXX	-YYY	XXX	x	YYY
Signal	11	-XXX	-YYY	XXX	x	YYY
Signal	12	-XXX	-YYY	XXX	x	YYY
Signal	13	XXX	-YYY	XXX	x	YYY
Signal	14	XXX	-YYY	XXX	x	YYY
Signal	15	XXX	-YYY	XXX	x	YYY
Signal	16	XXX	-YYY	XXX	x	YYY
Signal	17	XXX	-YYY	XXX	x	YYY
Signal	18	XXX	YYY	XXX	x	YYY
Signal	19	XXX	YYY	XXX	x	YYY
Signal	20	XXX	YYY	XXX	x	YYY
Signal	21	XXX	YYY	XXX	x	YYY
Signal	22	XXX	YYY	XXX	x	YYY
Signal	23	XXX	YYY	XXX	x	YYY
Signal	24	XXX	YYY	XXX	x	YYY

LMXXX MDA MWA EXAMPLE DIE DATASHEET
DEVICE DISCRIPTION

Life Support Policy

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety of effectiveness.



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